

Title (en)  
GOLD ELECTROPLATING BATH

Publication  
**EP 0188386 A3 19861008 (EN)**

Application  
**EP 86300301 A 19860117**

Priority  
GB 8501245 A 19850118

Abstract (en)  
[origin: EP0188386A2] An acid gold electroplating bath contains gold in an electrodepositable form, such as potassium gold cyanide, together with a metallic additive and an organic additive. The organic additive is a compound of the formula <CHEM> wherein X is -N= or -CR<3>=, and R<1>, R<2> and R<3> are each hydrogen, or an amino-, amido, thioamido- or cyano- group provided that one (and no more than one) of R<1>, R<2> and R<3> is not hydrogen. The metallic additive is preferably a cobalt, nickel or iron salt.

IPC 1-7  
**C25D 3/62**; **C25D 3/48**

IPC 8 full level  
**C25D 3/48** (2006.01); **C25D 3/56** (2006.01); **C25D 3/62** (2006.01)

CPC (source: EP)  
**C25D 3/48** (2013.01); **C25D 3/62** (2013.01)

Citation (search report)

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